

**Qualification Results Summary of LTM4633, LTM4634 with revised substrate and Sumitomo G311E mold compound**

QUALIFICATION STATUS – LTM4633 BGA			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
Thermal Shock (TS)*	JEDEC <i>JESD22-A106</i>	<b>1*200</b>	<b>Pass</b>
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	<b>1*200</b>	<b>Pass</b>

\*Preconditioned per JEDEC/IPC J-STD-020 MSL3 (@245C)

**Qualification Results Summary of LTM4633, LTM4634 with revised substrate and Sumitomo G311E mold compound**

QUALIFICATION STATUS – LTM4634 BGA			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
Unbiased Highly Accelerated Stress Test (UHAST)*	JEDEC <i>JESD22-A102</i>	<b>1*77</b>	<b>Pass</b>
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	<b>1*77</b>	<b>Pass</b>
Thermal Shock (TS)*	JEDEC <i>JESD22-A106</i>	<b>1*77</b>	<b>Pass</b>
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	<b>1*231</b>	<b>Pass</b>

\*Preconditioned per JEDEC/IPC J-STD-020 MSL3 (@245C)